

RELIABILITY REPORT
FOR
MAX6447UKxxL
PLASTIC ENCAPSULATED DEVICES

June 2, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

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Conclusion

The MAX6447 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX6447 low-current microprocessor reset circuit features single or reset inputs with an extended 6.72s setup period. Because of the extended setup period, short switch closures (nuisance resets) is ignored.

The reset output asserts when any of the monitored supply voltages drops below its specified threshold. The reset output remains asserted for the reset timeout period (210ms typ) after all monitored supplies exceed their reset thresholds. The reset output is one-shot pulse asserted for the reset timeout period (140ms min) when selected manual reset input(s) are held low for an extended setup timeout period of 6.72s. This device ignores manual reset transitions of less than 6.72s (typ).

The MAX6447 is a single fixed-voltage μ P supervisor. The MAX6447 has one extended and one immediate manual reset input.

The MAX6447 has an active-low RESET-bar with a push-pull output logic option. This device, offered in small SOT packages, is fully guaranteed over the extended temperature range (-40°C to +85°C).

B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
All Voltages Referenced to GND	
VCC	-0.3V to +6V
Push-Pull RESET	-0.3V to (VCC + 0.3V)
MR1, MR2, MR2, RSTIN	-0.3V to +6V
Input Current, All Pins	\pm 20mA
Operating Temperature Range	-40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
5-Pin SOT23	571mW
Derates above +70°C	
5-Pin SOT23	7.1mW/°C

II. Manufacturing Information

A. Description/Function:	μ P Reset Circuits with Long Manual Reset Setup Period
B. Process:	B8 (Standard 0.8 micron silicon gate CMOS)
C. Number of Device Transistors:	1384
D. Fabrication Location:	California, USA
E. Assembly Location:	Malaysia or Thailand
F. Date of Initial Production:	January, 2003

III. Packaging Information

A. Package Type:	5-Pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-1601-0197
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112:	Level 1

IV. Die Information

A. Dimensions:	31 x 44 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)
Bryan Preeshl (Executive Director)
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 93 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

▲
Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 11.68 \times 10^{-9}$$

$$\lambda = 11.68 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-6074) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The MS76 die type has been found to have all pins able to withstand a transient pulse of $\pm 1500\text{V}$ per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 250\text{mA}$.

Table 1
Reliability Evaluation Test Results

MAX6447UKxxL

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		93	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	SOT23	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} <u>3/</u>	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

2/ No connects are not to be tested.

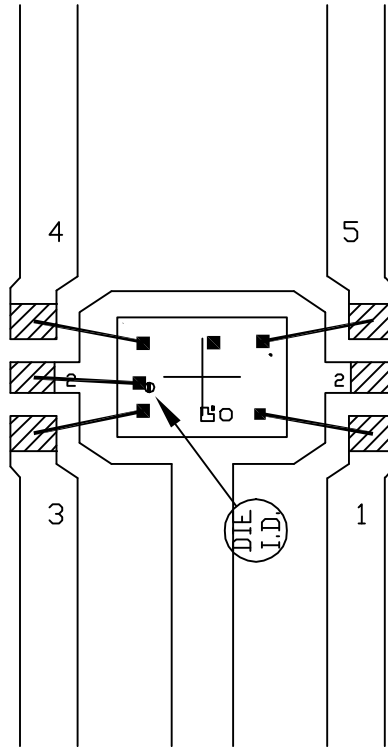
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, $+V_S$, $-V_S$, V_{REF} , etc).

3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





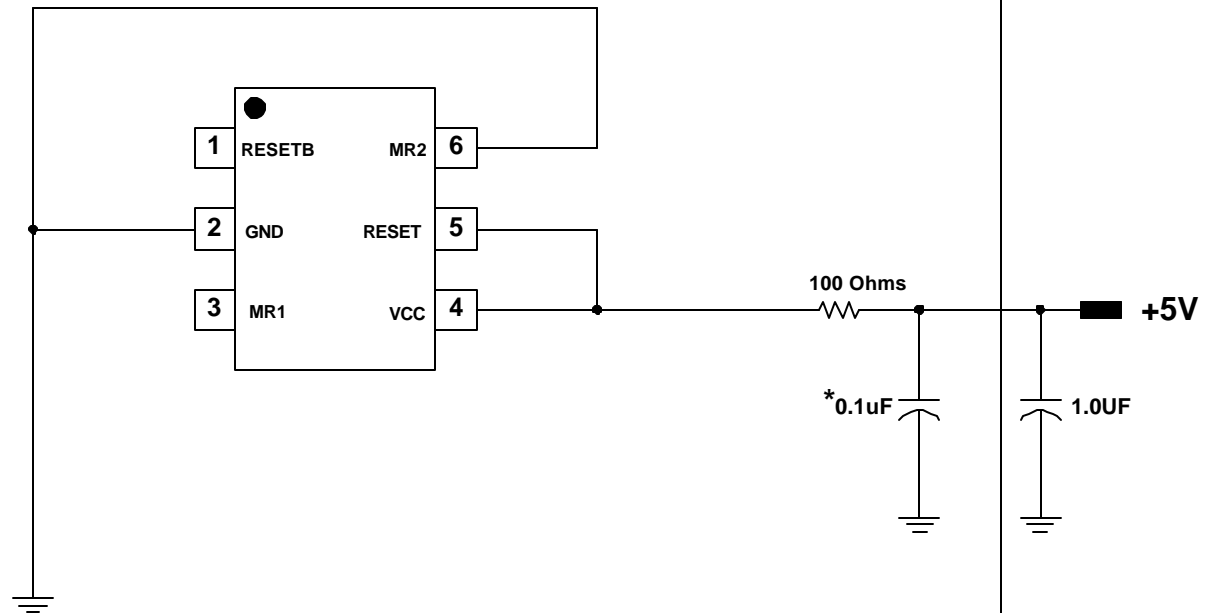
▨ - BONDING AREA

NOTE: CAVITY DOWN

PKG. CODE: U5-1		SIGNATURES	DATE	 CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 64X45	PKG. DESIGN			BOND DIAGRAM #: 05-1601-0197	REV: A

ONCE PER SOCKET

ONCE PER BOARD



DEVICES: MAX 6449-6456(MS76Z)
PACKAGE: 6-SOT
MAX. EXPECTED CURRENT = 200uA

DRAWN BY: TEK TAN
NOTES: *ONCE PER ROW.